

RCX511N25

Nch 250V 51A Power MOSFET

V_{DSS}	250V
R _{DS(on)} (Max.)	$65 \mathrm{m}\Omega$
I _D	51A
P_D	84W

Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Drive circuits can be simple.
- 4) Parallel use is easy.
- 5) Pb-free lead plating; RoHS compliant
- 6) 100% Avalanche tested

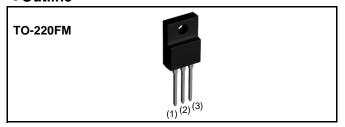
Application

Switching Power Supply

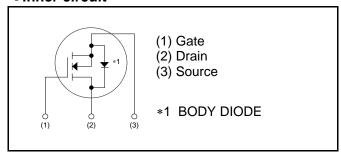
Automotive Motor Drive

Automotive Solenoid Drive

Outline



●Inner circuit



Packaging specifications

	Packaging	Bulk
	Reel size (mm)	-
Type	Tape width (mm)	-
Туре	Basic ordering unit (pcs)	500
	Taping code	-
	Marking	RCX511N25

• Absolute maximum ratings($T_a = 25$ °C)

Parameter	Symbol	Value	Unit	
Drain - Source voltage		V_{DSS}	250	V
Continuous drain current	$T_c = 25^{\circ}C$	I _D *1	±51	А
	T _c = 100°C	I _D *1	±27.7	А
Pulsed drain current	I _{D,pulse} *2	204	А	
Gate - Source voltage	V_{GSS}	±30	V	
Avalanche energy, single pulse		E _{AS} *3	197.9	mJ
Avalanche current		I _{AR} *3	25.5	А
T _c = 25°C		P _D	84	W
Power dissipation $T_a = 25$ °C		P _D	2.23	W
Junction temperature	T _j	150	°C	
Range of storage temperature	T _{stg}	-55 to +150	°C	

●Thermal resistance

Parameter	Symbol	Values			Unit
- Farameter	Symbol	Min.	Тур.	Max.	Offic
Thermal resistance, junction - case	R_{thJC}	-	-	1.48	°C/W
Thermal resistance, junction - ambient	R_{thJA}	-	-	56	°C/W
Soldering temperature, wavesoldering for 10s	T _{sold}	-	-	265	°C

•Electrical characteristics($T_a = 25$ °C)

Parameter	Symbol	Conditions	Values			Unit
Farameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V$, $I_D = 1mA$	250	-	-	V
Zero gate voltage drain current	I _{DSS}	$V_{DS} = 250V, V_{GS} = 0V$ $T_{j} = 25^{\circ}C$	-	-	10	μА
Gate - Source leakage current	I_{GSS}	$V_{GS} = \pm 30V, V_{DS} = 0V$	-	-	100	nA
Gate threshold voltage	V _{GS (th)}	$V_{DS} = 10V$, $I_D = 1mA$	3.0	-	5.0	V
		$V_{GS} = 10V, I_D = 25.5A$	-	48	65	
Static drain - source on - state resistance	R _{DS(on)} *4	$V_{GS} = 10V, I_D = 25.5A$ $T_j = 125^{\circ}C$	-	110	155	mΩ
Forward transfer admittance	g fs	$V_{DS} = 10V, I_{D} = 25.5A$	15	30	-	S

●Electrical characteristics(T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
r ai ai ii e lei	Syllibol	Symbol Conditions		Тур.	Max.	Offic
Input capacitance	C _{iss}	$V_{GS} = 0V$	-	7000	-	
Output capacitance	C _{oss}	V _{DS} = 25V	-	350	-	pF
Reverse transfer capacitance	C_{rss}	f = 1MHz	-	200	-	
Turn - on delay time	t _{d(on)} *4	$V_{DD} \simeq 125V, V_{GS} = 10V$	-	65	-	
Rise time	t _r *4	$I_D = 25.5A$	-	300	-	nc
Turn - off delay time	t _{d(off)} *4	$R_L = 4.7\Omega$	-	170	-	ns
Fall time	t _f *4	$R_G = 10\Omega$	-	210	-	

• Gate Charge characteristics ($T_a = 25$ °C)

Dorometer	Cymbal	Conditions	Values			l loit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Total gate charge	Q_g^{*4}	V _{DD} ≃ 125V	-	120	-	
Gate - Source charge	Q _{gs} *4	I _D = 51A	-	40	-	nC
Gate - Drain charge	Q _{gd} *4	V _{GS} = 10V	-	40	-	
Gate plateau voltage	V _(plateau)	$V_{DD} \simeq 125V, I_D = 51A$	-	6.5	-	V

●Body diode electrical characteristics (Source-Drain)(T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
r arameter	Symbol Conditions -		Min.	Тур.	Max.	Offic
Continuous source current	I _S *1	T _c = 25°C	-	-	51	Α
Pulsed source current	$I_{\rm SM}^{~*2}$	1 _c = 25 0	ı	ı	204	Α
Forward voltage	V_{SD}^{*4}	$V_{GS} = 0V, I_{S} = 51A$	-	-	1.5	V
Reverse recovery time	t _{rr} *4	I _S = 25.5A	-	175	-	ns
Reverse recovery charge	Q _{rr} *4	di/dt = 100A/μs	-	1100	-	nC

^{*1} Limited only by maximum temperature allowed.

^{*2} Pw \leq 10 μ s, Duty cycle \leq 1%

^{*3} L $^{\simeq}$ 500 μ H, V_{DD} = 50V, Rg = 25 Ω , starting T $_{j}$ = 25°C

^{*4} Pulsed

Fig.1 Power Dissipation Derating Curve

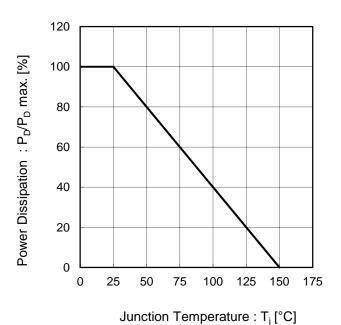
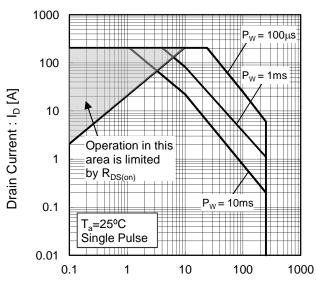
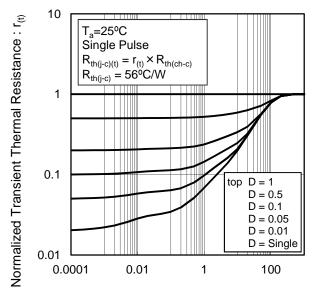


Fig.2 Maximum Safe Operating Area



Drain - Source Voltage : V_{DS} [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width



Pulse Width : $P_W[s]$

Fig.4 Avalanche Current vs Inductive Load

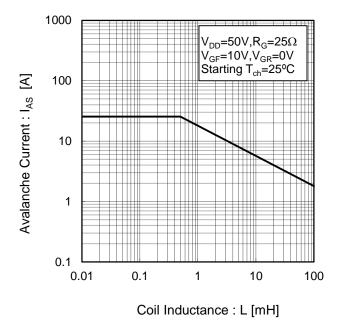
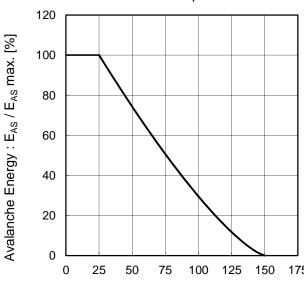
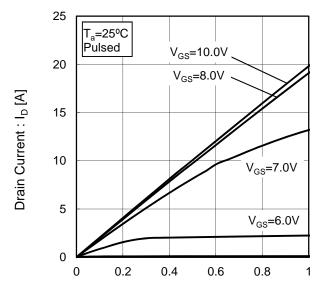


Fig.5 Avalanche Energy Derating Curve vs Junction Temperature



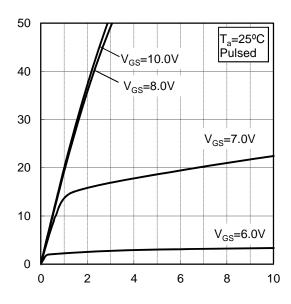
Junction Temperature : T_i [°C]

Fig.6 Typical Output Characteristics(I)



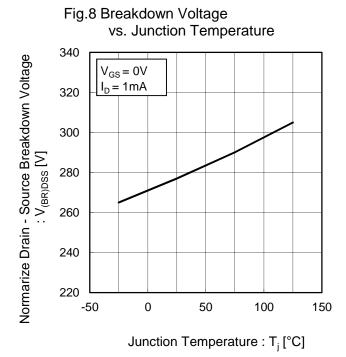
Drain - Source Voltage : V_{DS} [V]

Fig.7 Typical Output Characteristics(II)



Drain - Source Voltage : V_{DS} [V]

Drain Current : I_D [A]



100 $V_{DS} = 10V$ 10 Drain Current: I_D [A] $T_a = 125^{\circ}C$ $T_a = 75^{\circ}C$ $T_a = 25^{\circ}C$ 0.1 0.01 0.001

0

2 3 4 5 6

Fig.9 Typical Transfer Characteristics

Gate - Source Voltage : V_{GS} [V]

Fig.11 Transconductance vs. Drain Current

8

Fig.10 Gate Threshold Voltage vs. Junction Temperature 5.5 $V_{DS} = 10V$ $I_D = 1 \text{mA}$ 5.0

Gate Threshold Voltage: VGS(th) [V] 4.5 4.0 3.5 3.0 2.5 -50 50 100 125 150 -25 0 25 75 Junction Temperature : T_i [°C]

100 $V_{DS} = 10V$ 10 Transconductance: g_{fs} [S] Γ_a=25°C T_a=75°C T_a=125°C 0.1 0.01 0.01 0.1 1 10 100

Drain Current : I_D [A]

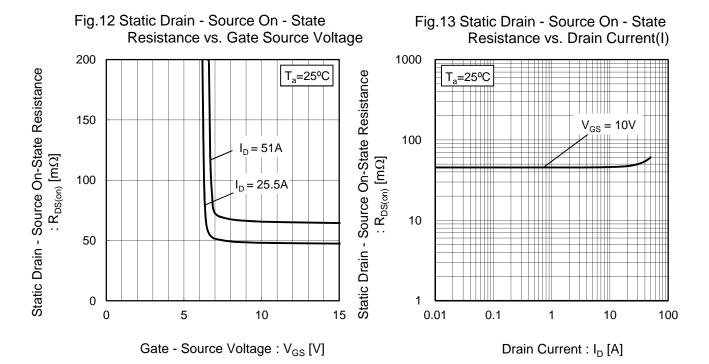
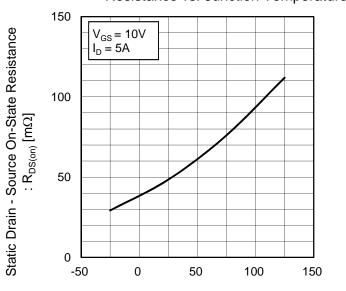


Fig.14 Static Drain - Source On - State Resistance vs. Junction Temperature



Junction Temperature : T_j [°C]

Fig.15 Static Drain - Source On - State Resistance vs. Drain Current(II)

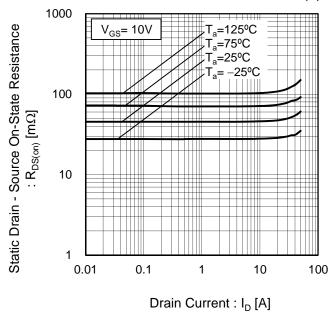


Fig.16 Drain Current Derating Curve

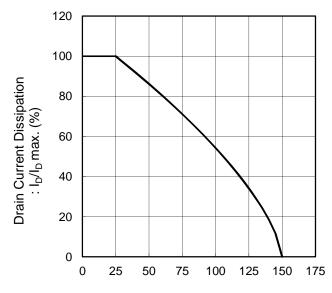
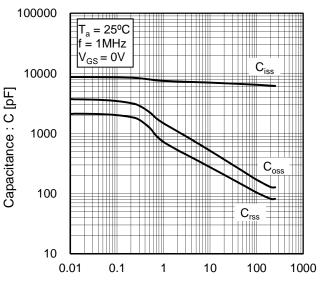


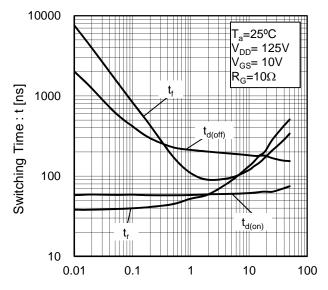
Fig.17 Typical Capacitance

vs. Drain - Source Voltage



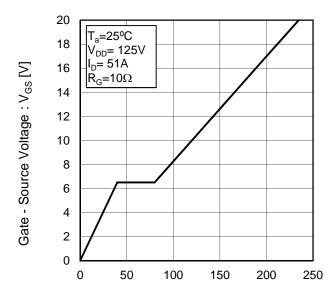
Drain - Source Voltage : V_{DS} [V]

Fig.18 Switching Characteristics



Drain Current : I_D [A]

Fig.19 Dynamic Input Characteristics



Total Gate Charge : Q_g [nC]

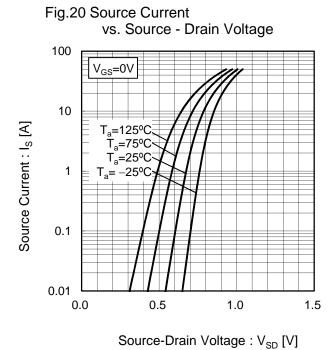


Fig21 Reverse Recovery Time
vs. Source Current

1000

Ta=25°C

di / dt = 100A / µs

V_{GS} = 0V

10

0.1

1
1
10
100

Source Current : I_S [A]

●Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

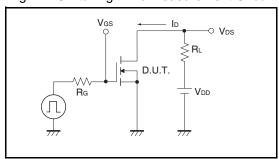


Fig.2-1 Gate Charge Measurement Circuit

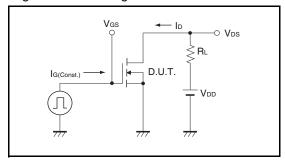


Fig.3-1 Avalanche Measurement Circuit

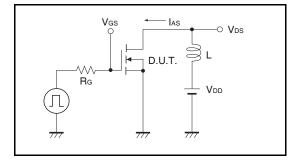


Fig.1-2 Switching Waveforms

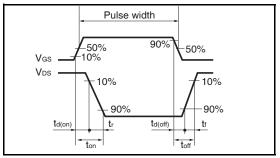


Fig.2-2 Gate Charge Waveform

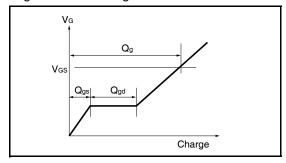
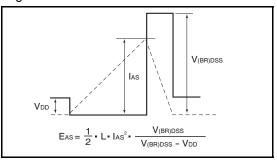
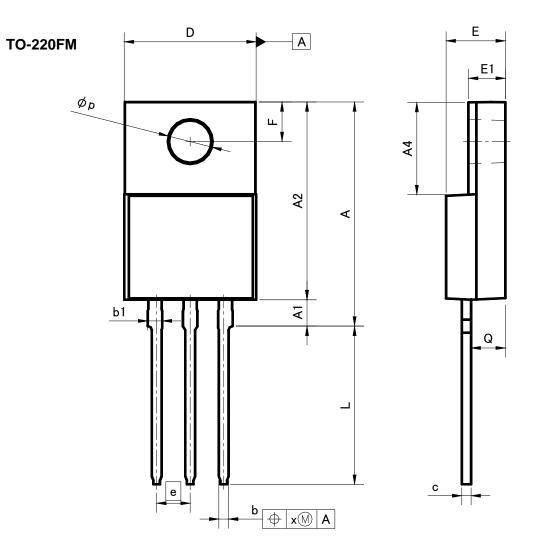


Fig.3-2 Avalanche Waveform



●Dimensions (Unit : mm)



DIM	MILIMETERS		INC	HES
DIIVI	MIN	MAX	MIN	MAX
Α	16.60	17.60	0.654	0.693
A1	1.80	2.20	0.071	0.087
A2	14.80	15.40	0.583	0.606
A4	6.80	7.20	0.268	0.283
b	0.70	0.85	0.028	0.033
b1	1.10	1.50	0.043	0.059
С	0.70	0.85	0.028	0.033
D	9.90	10.30	0.39	0.406
Е	4.40	4.80	0.173	0.189
е	2.54		0.	10
E1	2.70	3.00	0.106	0.118
F	2.80	3.20	0.11	0.126
L	11.50	12.50	0.453	0.492
р	3.00	3.40	0.118	0.134
Q	2.10	3.10	0.083	0.122
х	-	0.381	_	0.015

Dimension in mm/inches

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JAPAN	USA	EU	CHINA
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CLASSIV	CLASSIII	CLASSⅢ	CLASSII

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 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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